

TOSHIBA DIODE SILICON EPITAXIAL PLANAR DIODE

1SS398

HIGH VOLTAGE, HIGH SPEED SWITCHING APPLICATIONS.

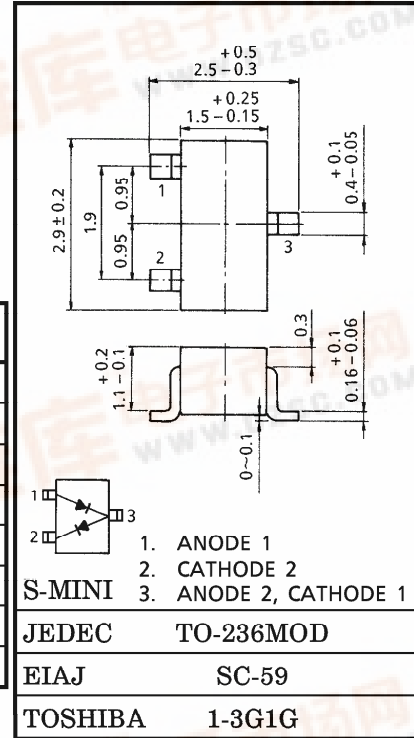
Unit in mm

- Low Forward Voltage : $V_F = 1.0V$ (Typ.)
- High Voltage : $V_R = 400V$ (Min.)
- Fast Reverse Recovery Time : $t_{rr} = 0.5\mu s$ (Typ.)
- Small Total Capacitance : $C_T = 2.5pF$ (Typ.)
- Small Package : SC-59

MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	V_{RM}	420	V
Reverse Voltage	V_R	400	V
Maximum (Peak) Forward Current	I_{FM}	300 *	mA
Average Forward Current	I_O	100 *	mA
Surge Current (10ms)	I_{FSM}	2 *	A
Power Dissipation	P	150	mW
Junction Temperature	T_j	125	$^\circ C$
Storage Temperature Range	T_{stg}	-55~125	$^\circ C$

* : Unit Rating. Total Rating = Unit Rating \times 0.7



ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ C$)

Weight : 0.012g

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_F(1)$	$I_F = 10mA$	—	0.8	—	V
	$V_F(2)$	$I_F = 100mA$	—	1.0	1.3	
Reverse Current	$I_R(1)$	$V_R = 300V$	—	—	0.1	μA
	$I_R(2)$	$V_R = 400V$	—	—	1.0	
Total Capacitance	C_T	$V_R = 0, f = 1MHz$	—	2.5	5.0	pF
Reverse Recovery Time	t_{rr}	$I_F = 10mA$ (Fig.1)	—	0.5	—	μs

EQUIVALENT CIRCUIT (TOP VIEW)

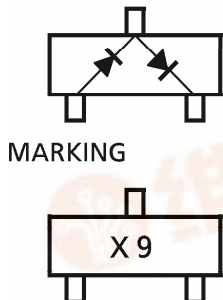
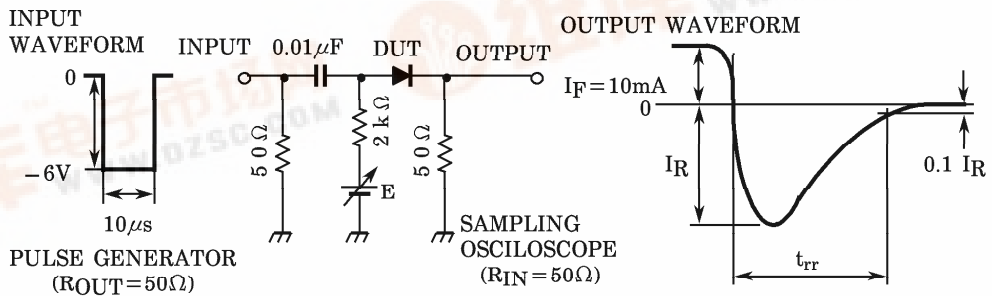
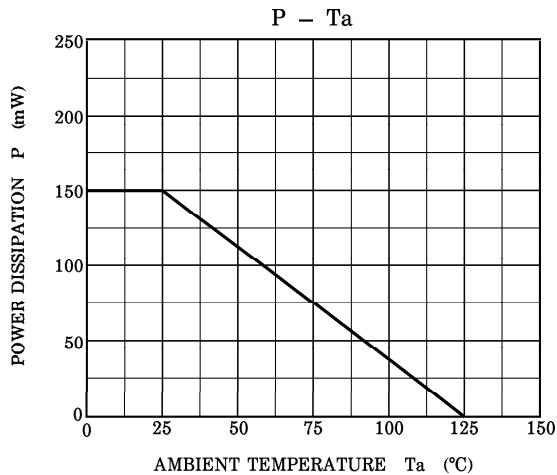
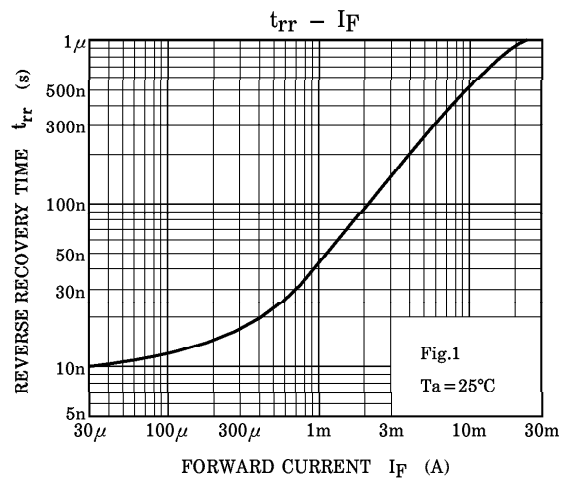
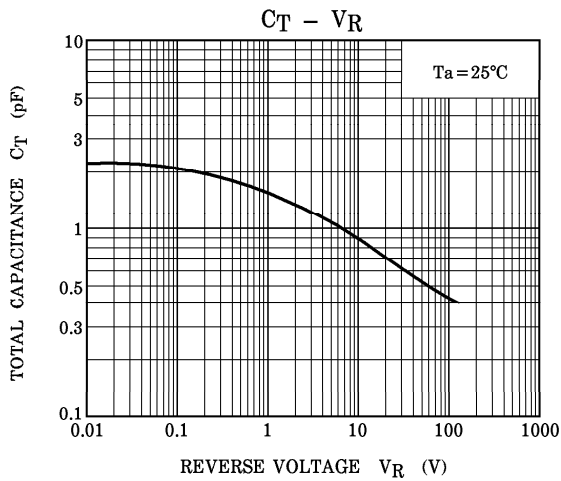
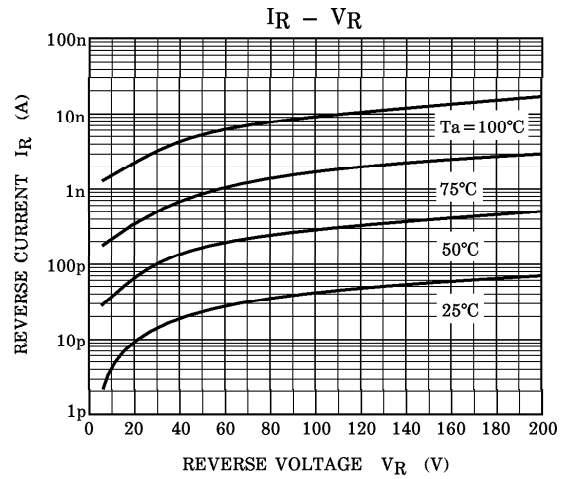
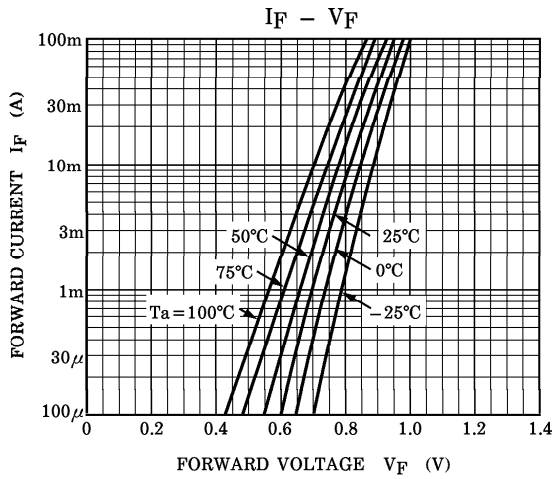


Fig1. REVERSE RECOVERY TIME (t_{rr}) TEST CIRCUIT



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